

SYSTEM AND METHOD FOR INSPECTING A WAFER

Abstract

An inspection system for inspecting a semiconductor wafer. The inspection system
5 comprises an illumination setup for supplying broadband illumination. The broadband
illumination can be of different contrasts, for example brightfield and darkfield
broadband illumination. The inspection system further comprises a first image capture
device and a second image capture device, each configured for receiving broadband
illumination to capture images of the semiconductor wafer while the semiconductor
10 wafer is in motion. The system comprises a number of tube lenses for enabling
collimation of the broadband illumination. The system also comprises a stabilizing
mechanism and an objective lens assembly. The system further comprises a thin line
illumination emitter and a third image capture device for receiving thin line illumination
to thereby capture three-dimensional images of the semiconductor wafer. The system
15 comprises a reflector assembly for enabling the third image capture device to receive
illumination reflected from the semiconductor wafer in multiple directions.

Figure 1